# 1 Fully automated, sequential focused ion beam milling

# 2 for cryo-electron tomography

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#### 22 Abstract

23 Cryo-electron tomography (cryoET) has become a powerful technique at the interface of 24 structural biology and cell biology, with the unique ability to determine structures of 25 macromolecular complexes in their cellular context. A major limitation of cryoET is its 26 restriction to relatively thin samples. Sample thinning by cryo-focused ion beam 27 (cryoFIB) milling has significantly expanded the range of samples that can be analyzed 28 by cryoET. Unfortunately, cryoFIB milling is low-throughput, time-consuming and 29 manual. Here we report a method for fully automated sequential cryoFIB preparation of 30 high-quality lamellae, including rough milling and polishing. We reproducibly applied 31 this method to eukaryotic and bacterial model organisms, and show that the resulting 32 lamellae are suitable for cryoET imaging and subtomogram averaging. Since our method 33 reduces the time required for lamella preparation and minimizes the need for user input, 34 we envision the technique will render previously inaccessible projects feasible.

#### 35 Introduction

Cryo-electron tomography (cryoET) is a powerful imaging technique at the interface of 36 37 cell biology and structural biology, able to image cells in a near-native state and determine 38 the structure of macromolecular machines in their cellular context (Beck and Baumeister, 39 2016; Koning et al., 2018; Kooger et al., 2018; Oikonomou and Jensen, 2017; Plitzko et 40 al., 2017). CryoET is restricted to samples that are well below 800 nm in thickness and 41 therefore requires sample thinning techniques for specimens like mammalian cells, C. 42 elegans, yeast, cyanobacteria, or biofilms. Biological cryoFIB milling is an emerging 43 sample thinning technique, which uses a Gallium ion beam to ablate segments of the 44 sample in order to generate thin lamellae that can be imaged by cryoET (Marko et al., 45 2007; Rigort et al., 2010). Unlike previous methodologies, cryoFIB milling produces 46 artifact-free specimens, in which in situ structural information is preserved. Its application 47 has led to important insights into mechanisms of cellular function (Albert et al., 2017; 48 Böck et al., 2017; Bykov et al., 2017; Cai et al., 2018; Chaikeeratisak et al., 2019; Delarue 49 et al., 2018; Khanna et al., 2019; Mahamid et al., 2016; Rast et al., 2019; Swulius et al., 50 2018; Weiss et al., 2019). Unfortunately, however, cryoFIB milling for cryoET is at an 51 early stage of technical maturation and the available techniques are highly manual 52 procedures with relatively low throughput.

53 In current lamella preparation workflows (Marko et al., 2007; Medeiros et al., 2018; 54 Rigort et al., 2010; Strunk et al., 2012; Zhang et al., 2016), samples are vitrified on 55 transmission electron microscopy (TEM) grids by plunge-freezing. Grids are then 56 transferred to a FIB-scanning electron microscope (SEM) instrument, where potential 57 targets are then identified by SEM and FIB imaging (Supplementary Fig. 1a/b). Using a 58 series of 'rough milling' steps, sections above and below the desired lamella are 59 sequentially removed by decreasing the separation between two milling areas and using 60 decreasing FIB milling currents (700 to 100 pA) (Supplementary Fig. 1c-e). Once the 61 lamella is thinned to ~500 nm, additional targets are identified and thinned by rough 62 milling in a similar manner. To generate lamellae with a final thickness of 100-250 nm, 63 the user returns to each target location and further thins ('polishes') each lamella using a 64 low ( $\leq$ 50 pA) current (Supplementary Fig. 1f).

This methodology allows the production of up to 16 lamellae in 10 h (Medeiros et al.,2018), however, during such a session, the process requires constant attention from the

operator. The milling process has to be monitored and manual user input is required every 10-15 min, e.g. to execute a series of repetitive tasks such as target identification, positioning milling patterns, changing FIB currents, and visually determining milling end points. This results in a strenuous procedure with a low throughput relative to the time invested by the user, as well as significant idle times due to delays in input from the operator. To overcome these issues, automated sequential cryoFIB milling has become of paramount interest for the field.

## 74 Setup of an automated milling session

75 Here we report, to our knowledge, the first automated sequential FIB milling method for 76 the preparation of lamellae for subsequent cryoET imaging. Automation was 77 implemented on the Zeiss Crossbeam 550 FIB-SEM instrument, using routines that are 78 available in the SmartFIB software package (Zeiss Microscopy GmbH, Oberkochen, 79 Germany). Particularly important are the modules for stage backlash and drift correction, 80 which are critical for reliable targeting of lamella preparation sites. This allows the user 81 to set up all milling targets and then execute milling in an unattended, fully automated 82 manner.

83 To begin an automated milling session, FIB current alignments are verified to ensure 84 accurate milling (Fig. 1a). Grids are then loaded into the FIB-SEM instrument. To 85 simplify navigation and target identification, an SEM grid overview image is captured 86 and linked to the stage coordinates as described in the methods. Using the overview image 87 for stage navigation, the first milling site is identified and centered in both the SEM and 88 FIB views (Fig. 1b). To improve the accuracy of mechanical stage movements, the stage 89 is backlash-corrected when moved during automation. To ensure accurate targeting of the 90 milling site, a series of operations is executed before saving the final target position (Fig. 91 1c). First, stage backlash correction is manually executed and the target is re-centered in 92 the FIB image. Second, the target's stage coordinates are saved to the stage navigation 93 menu. Third, the stage is manually moved off-target and automatically returned to the 94 saved target location (Fig. 1d). In case the target is not properly centered, the above three 95 steps are repeated (Fig. 1e), otherwise the user can proceed.

Next, patterns with specific currents for rough milling (e.g. 700, 300 and 100 pA) and
polishing (e.g. 50 pA) are manually placed onto the FIB image of the target (Fig. 1f/f').

This is achieved by either generating a new set of patterns or by loading previously designed patterns, which is faster and results in more uniform lamellae. To further improve the accuracy of targeting, we incorporated an additional targeting step based on drift correction (Fig. 1f/f'). To implement, each set of milling patterns receives a drift correction box, with user-defined dimensions, which is manually placed in a location close to the target. By capturing and saving an image of the drift correction box, the milling patterns are anchored to their positions on the target.

After saving the first target to the queue, further targets are added by repeating the
described procedure. This setup-procedure takes ~9 min per target.

## 107 Processes during automated milling session

108 To begin sequential automation, exposure of the rough milling patterns that are saved in 109 the queue is started (Fig. 1g). For each target, the stage automatically moves to the target 110 position and executes stage backlash correction. Next, image shifts are determined 111 between the drift correction image that was recorded during the setup procedure and a 112 drift correction image that is recorded after arriving at the target location. Any existing shifts are compensated for, using FIB beam shifts, to improve the precision of milling. 113 114 The rough milling patterns are then exposed, from the highest to the lowest current 115 strength. Previously, manual milling methods used a real-time view in order to determine 116 the time that the FIB needs to cut through the specimen. In our automated approach, the 117 exposure time is calculated by the software using a user-specified milling depth (typically 118 10 µm), milling current, pattern size and material type (e.g. vitrified ice). After exposing 119 the rough milling patterns for the first target, the procedure is automatically repeated for 120 the remaining targets.

Subsequently, the user can decide whether to perform polishing for all targets in a manual
or automated manner (Fig. 1h). The automation of polishing follows the routine described
above.

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#### 127 Application of sequential automated milling

128 During the development of this method, we tested automated sequential milling using the 129 model organisms S. cerevisiae strain SK1 (hereafter yeast) and the multicellular 130 cyanobacteria Anabaena sp. PCC 7120 (hereafter Anabaena) in six independent milling 131 sessions (Table 1). The number of attempted lamellae per session ranged from five to 20 132 (Fig. 2). Rough milling success, as defined by the presence of a lamella at the targeted 133 location after rough milling, was 99% (n=73). The only failure in lamella production was 134 the result of a user error, as rough milling was accidentally executed on the same target 135 twice (session F). In session B.1 and B.2, lamellae were successfully generated on ten 136 targets that were spread across two grids containing two different samples (Table 1). This 137 shows the robustness of the targeting routine despite sample variations and the execution 138 of large stage movements during automation.

139 While these results present a significant step forward, we next set out to implement 140 automated sequential lamella polishing. In a series of sessions (B.2-F), we milled between 141 five and 20 targets. In total, the success rate (intact lamella detected after polishing) of automated sequential polishing was 81% (n=57 rough lamellae). Importantly, 9 of the 11 142 143 failed polishing attempts occurred in session C, in which the rough-milled lamellae were 144 left in the FIB-SEM instrument for 10 h before automated polishing was started. Prior to 145 polishing, these rough lamellae showed signs of bending, which likely resulted in failure 146 in lamellae polishing. Sequential automated lamella polishing should therefore be 147 executed without delay after rough milling. Other reasons for failure in lamella milling could include sample heterogeneity and errors in targeting. If, however, session C were 148 149 not taken into account, this automated sequential FIB milling methodology would have a 150 95% (n=37) success rate.

#### 151 Assessment of sample quality

152 In order to assess sample quality, we transferred the grids from all sessions to the 153 cryoTEM. Of the lamellae that were generated in a fully automated manner, 11% (n=46) 154 were lost in transfer. All remaining lamellae could be imaged by cryoET. From the 155 cryotomograms, we determined the lamellae thicknesses to range from 155 to 379 nm 156 (average 232 nm; final polishing patterns were spaced 300 nm apart) (Supplementary Fig. 157 2). Lamellae that were manually polished (sessions A/B.1) had a comparable average158 thickness of 258 nm (final polishing patterns were spaced 300 nm apart).

159 CryoET imaging of the automatically generated lamellae revealed distinct cellular 160 features and macromolecular complexes. Yeast tomograms showed a characteristic 161 nucleoplasm, cytoplasmic ribosomes, nuclear envelope, nuclear pore complexes, and 162 cellular compartments (Fig. 3b). Anabaena tomograms showed thylakoid membranes, 163 phycobilisomes and septal junctions (Fig. 3c). To further assess sample and data quality, 164 we performed subtomogram averaging of Anabaena septal junctions, which had been 165 characterized recently by a manual cryoFIB milling/cryoET approach (Weiss et al., 166 2019). From nine lamellae, a total of 412 subvolumes were extracted, averaged and 167 classified in order to remove misaligned particles. The 343 remaining subvolumes were 168 then averaged and symmetrized. The resulting structure revealed key features, including 169 a cap module with five arches, a plug module and a tube module (Fig. 3e-h). Fourier shell 170 correlation (FSC) analyses indicate that the average has a resolution that is similar to a 171 structure that was calculated using the same number of particles extracted from 172 tomograms generated in a previous study (Weiss et al., 2019) (manual milling) 173 (Supplementary Fig. 3).

## 174 Discussion

175 In conclusion, our automated sequential cryoFIB milling method allows for the 176 production of high-quality lamellae for cryoET imaging and will impact cryoFIB/cryoET 177 projects in several ways. First, the time investment by the operator is significantly reduced 178 from  $\sim 10$  h in a manual milling session to  $\sim 2.4$  h for an automated sequential milling 179 session, assuming 16 targets are milled. Second, by removing the need for frequent user 180 inputs and idle times, the minimum required machine time is reduced from ~38 min 181 (Medeiros et al., 2018) (i.e. 16 lamellae in 10 h) to ~25.5 min (9 min setup plus 16.5 min 182 milling) per lamella. Third, based on the robustness and customizable nature of the 183 method, the procedure can be adapted to a wide range of samples and milling techniques 184 (Toro-Nahuelpan et al.; Wolff et al., 2019). Fourth, the automated procedure will allow 185 the user to systematically explore novel milling methods by reusing uniform milling 186 patterns. Fifth, the method can generally be combined with correlated approaches that 187 allow for target pre-screening, for instance cryo-light microscopy or cryo-FIB-SEM 188 volume imaging (Eibauer et al., 2012; Gorelick et al., 2019; Koning et al., 2014; Schertel et al., 2013; Schorb et al., 2017; Sviben et al., 2016; Vidavsky et al., 2016). That said, the
higher throughput achieved by automated cryoFIB milling (shown here) in combination
with fast cryoET data collection schemes (Chreifi et al., 2019; Eisenstein et al., 2019),
might in many cases eliminate the need for target pre-identification by correlated
approaches. Altogether, the development of automated sequential cryoFIB milling
renders cryoET applicable to previously unfeasible projects.

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#### 203 Methods

#### 204 Overview of the equipment and workflow

205 The method was established and tested on a Crossbeam 550 FIB-SEM instrument (Carl 206 Zeiss Microscopy) equipped with a copper band-cooled mechanical cryo-stage and an 207 integrated VCT500 vacuum transfer system (Leica Microsystems). The detectors used 208 included an InLens secondary elelctron (SE) detector for determining grid topology (Carl 209 Zeiss Microscopy) and a SE2 detector for identifying milling targets and assessing the ice 210 thickness (Carl Zeiss Microscopy). In our workflow, EM grids were prepared with 211 budding yeast strain SK1 and Anabaena sp. PCC 7120, and clipped into FIB milling 212 Autogrids (ThermoFisher Scientific, Waltham, Massachusetts, U.S.). These grids were 213 then mounted onto a pre-tilted Autogrid holder (Medeiros et al., 2018) (Leica 214 Microsystems) using a VCM loading station (Leica Microsystems). Using the VCT500 215 shuttle, the Autogrid holder was transferred to an ACE600 cryo-sputter coater (Leica 216 Microsystems) under cryogenic conditions and the samples were sputter-coated with a 4 217 nm thick layer of tungsten. After sputter coating, the samples were transferred into the Crossbeam 550 using the VCT500 shuttle. In the Crossbeam 550, the gas injection system 218 219 (UniGIS) was used to deposit an organometallic platinum precursor layer onto each grid. 220 Automated sequential FIB milling was subsequently set up and executed. Sample 221 preparation, plunge-freezing, Autogrid mounting, holder loading and vacuum cryo-222 transfer steps were executed similarly to what was described in Medeiros et al. 2018. Any 223 deviations to the previously published protocol are described below.

224 Cell culture and plunge freezing

FIB milling tests were performed using the cyanobacterial strain *Anabaena* sp. PCC 7120 and the *S. cerevisiae* strain SK1. The *Anabaena* strain was grown and prepared for FIB milling as previously described in Weiss et al. 2019. Yeast cells were prepared as previously described by Medeiros et al. 2018.

229 Equipment calibration

To ensure that automated sequential FIB milling was successful, the Crossbeam 550 was properly aligned. While the SEM column alignments are stable and non-essential during automated milling, the FIB alignment between different currents at a given voltage (30 233 kV for biological cryo-samples) should be checked and optimized. Typically, this 234 calibration is done weekly or when deemed necessary and takes roughly 60 min to 235 complete. In case of deviation, on-the-fly adjustments are possible on a loaded cryo-236 sample, however, standard calibration procedures are best performed on a silicon wafer 237 due to its structural homogeneity, which allows better evaluation of the FIB beam shape. Once inserted into the chamber, the stage was tilted by 54° to be perpendicular to the FIB 238 239 beam and then moved to the working distance (i.e. coincidence point). Using the 'spot' function in an unexposed sample region, the beam was focused to its spot size allowing 240 241 it to burn a hole into the silicon. If the current is properly calibrated, then the beam will 242 produce a spot that is round with sharp edges. This was best seen when using a mixed 243 signal of the InLens and SE2 detector. If a beam spot had imperfections, like a tailing 244 edge, beam parameters including focus, stigmatism and aperture alignments need to be 245 improved and saved. After optimizing these parameters for each current, all currents were 246 aligned against the reference current. This was best performed by centering an easily 247 recognizable structure like a burnt hole for each beam onto the exact position in the image 248 taken with the reference current. Finally, to ensure that the currents were properly aligned, 249 a location is imaged by each current. If properly aligned, switching between currents 250 should not lead to focus changes or beam offsets.

### 251 Sample coating

252 To enhance sample conductivity and decrease the effects of charging, EM grids were 253 coated with a ~4 nm layer of tungsten using the sputter coating head on the ACE600. 254 After inserting the holder into the FIB-SEM, a protection layer of organometallic 255 platinum precursor was deposited onto each grid to minimize the curtaining effect. For 256 cold deposition of platinum precursor, the holder was moved 3 mm below the coincidence 257 point and was tilted to 20 degrees. By positioning the gas injection system (GIS) needle above each grid and opening the GIS for 30 s, a layer of platinum precursor was deposited 258 259 onto the sample. Since the GIS needle was mounted at a similar angle as the FIB column, 260 deposition of platinum occurred preferentially on the side of the cells where the FIB beam 261 hits the sample, ensuring the best protection. For deposition under cryo-conditions, it is 262 essential that the heating element of the GIS needle and reservoir are turned off to keep 263 the system at room temperature (28 °C).

#### 265 Stage registration

266 To assist in the identification of targets, overview images of an entire EM grid are taken. 267 On the Zeiss Crossbeam 550, these images can be coupled to the stage navigation. To 268 calibrate stage registration a high-resolution (4096 x 3072 pixels, 35x) overview image 269 was taken with the SE2 detector, which provided the best information for identifying 270 targets inside the vitrified ice and determining ice thickness. This overview image was 271 then loaded onto the stage navigation bar and registered by correlating three distinctive 272 points on the image to their specific positions on the stage as observed in the live SEM 273 view. After completion, double clicking on a desired target image location in the 274 navigation bar automatically moves the stage to the location of interest. In addition, 275 backlash correction was also included for all automated stage movements, using the user 276 preference settings of the software SmartSEM (Carl Zeiss Microscopy).

## 277 Defining milling materials

To permit unsupervised automation of lamellae production, the Crossbeam 550 was calibrated to mill a cross-section with a specified depth through the sample. To ensure proper milling, the system needs to be calibrated for a distinct 'material' so that the correct milling parameters like dose are applied during milling. For cryo-TEM lamella preparation the material "vitrified ice" was created using a dose calibration of 20 mC / cm<sup>2</sup> being equivalent to a milling depth of 1  $\mu$ m in cross-section mode.

## 284 Parameters for imaging and milling

285 For SEM imaging, voltages from 1.9 - 5 kV and a constant current of 28 pA were used. 286 To capture SEM images, we most commonly used the InLens detector to obtain surface 287 information of the sample. During FIB imaging, on the other hand, a fixed voltage of 30 288 kV and a low current (20pA) was used. FIB images were usually captured by using the 289 SE2 detector, which is less sensitive to imaging-induced charging. During automated 290 sequential milling, four sets of currents above and below the desired lamellae were used. 291 For rough milling 700 pA, 300 pA and 100 pA currents were implemented. To then polish 292 the lamellae, a 50 pA current was used. For milling, we defined the patterns to be executed 293 using bi-directional and cross-section cycle mode with a 10 µm milling depth.

#### 295 Automated sequential FIB milling protocol

To generate high quality lamellae, it was essential to prepare the FIB-SEM and sample for automated sequential milling. Preparations included checking and calibrating the FIB currents, coating the sample with a layer of tungsten and organometallic platinum, and performing stage registration. Once these steps were executed, automated sequential milling was initiated by identifying and setting up milling targets.

301 The grid overview image in the stage navigator was used to identify a milling target. The 302 identified target was then manually centered in the live FIB view with the aid of the SEM. 303 To improve the accuracy of automated stage movements, backlash correction was 304 performed manually and implemented for all automated stage movements. The target's 305 stage coordinates were then saved in the stage navigator. To ensure that the instrument 306 was able to perform targeting during automation, the stage was manually moved away 307 from the target and then instructed to move back to its saved location. The target was 308 located using the live FIB view and if necessary, manually centered again. If manual 309 centering was required, the new stage location was saved and the instrument's ability to 310 perform targeting was tested again. To ensure successful milling during automation, it 311 was essential to refine the stage location until the stage was able to perform targeting 312 successfully.

313 Once an accurate stage movement was achieved, milling patterns were placed onto a 314 target FIB image captured using SmartFIB. In SmartFIB, each pattern contains specific 315 milling conditions (i.e. current, milling depth, size, shape, etc.) and a designated FIB 316 milling location. SmartFIB allows the placing of multiple patterns with different 317 conditions onto a single FIB image in order to perform automated milling. Patterns were 318 placed and their properties were changed by using the SmartFIB GUI in the 'Attributes' 319 tab. When testing this methodology, we placed eight rectangular milling patterns: six 320 rough milling and two polishing patterns (Supplementary table 1). The final polishing 321 patterns were spaced 300 nm apart, which from our experience results in an average 322 lamella thickness of 225-275 nm. To make uniform lamellae it was also possible to save 323 these eight patterns as a recipe, which can be dragged and dropped onto images of other 324 milling targets. To then save these milling patterns, it was essential to separate the rough 325 and polishing patterns. This was accomplished by deleting the polishing patterns from 326 our recipe, saving only the rough milling patterns, undoing the deletion of the polishing patterns (using the SmartFIB Undo button), deleting all rough milling patterns and thensaving only the polishing patterns.

329 To improve the targeting accuracy of this methodology, a drift correction step was also 330 added to each set of rough and polishing milling patterns immediately before being saved. 331 This was done in the SmartFIB 'attributes' tab, by capturing and saving an image of a 332 defined region of the FIB view. During the automated protocol SmartFIB would use this 333 image to perform image recognition before beginning milling and compensate for small 334 shifts to ensure the milling patterns are placed correctly on the target. When testing this 335 methodology, it was important to save and then load the same drift correction image for both the rough and polishing milling patterns. This ensured the highest accuracy when 336 337 moving from rough milling to polishing.

After saving a set of rough and polishing patterns, the described method can be repeated 338 339 for further targets. For an automated protocol, about 9 min were needed to set up each 340 target. It is possible to also automate the milling of targets found on separate EM grids. 341 Once satisfied with the number of targets, all rough milling recipes in the SmartFIB queue 342 were selected and exposed. Exposure of a typical rough milling target takes about 12 343 min. Upon completion, rough milling targets were observed using the SEM and FIB to 344 determine their quality. To then initiate polishing, it is possible to either tick all polishing 345 recipes and expose them, or individually move to each target using SmartFIB, take a FIB 346 image, manually drag polishing patterns into place and expose the lamella. Polishing 347 typically took about 4.5 min. Once all targets are polished, the lamellae are removed from 348 the instrument and stored. It is essential to note that we aimed to keep the lamellae in the 349 instrument for <2 h after beginning polishing to minimize contamination. In theory, this 350 limits our lamellae production to  $\leq 20$  targets. If, however, aspects including the milling 351 depth, pattern sizes or currents were changed, it would be possible to generate more 352 lamellae. Note that in our attempts, grids with milled lamellae were transported in a dry-353 shipper from Zeiss Oberkochen, Germany to Zürich, Switzerland prior to cryoET 354 imaging, possibly resulting in some lamellae breaking. An overview of all the milling 355 attempts performed can be found in Table 1.

356 Cryo-electron tomography, tomogram reconstruction and subtomogram averaging

357 Data was collected on a Titan Krios 300kV electron microscope (ThermoFisher)
358 equipped with a field emission gun, imaging filter (Gatan, Munich, Germany) (slit width

359 20 eV) and K2 Summit direct electron detector (Gatan). To generate an overview of each 360 grid, grid montages were collected at 135x magnification using SerialEM (Mastronarde, 361 2005). UCSF Tomo (Zheng et al., 2007) was used for automated recording of tilt series 362 (+60° and -60° tilt range, 2° increments). Data was collected at a defocus of -8 µm, total accumulated dose of  $\sim 140 \text{ e}^{-}/\text{Å}^{2}$  and pixel size of 3.38 Å. Tomogram reconstruction and 363 364 subtomogram averaging was performed according to Weiss et al. 2019. Briefly, 365 tomograms were reconstructed using the IMOD package (Kremer et al., 1996) and 366 subtomogram averaging was performed using PEET (Nicastro et al., 2006). A total of 412 particles were extracted and averaged in a box of 44 x 44 x 44 pixels with a pixel size of 367 368 0.68 nm. PEET classification was then used to remove misaligned particles (343 final 369 particles). 5-fold symmetry was applied to obtain the final average. The FSC (Fourier 370 Shell Correlation) was generated by using the PEET command calcFSC.

371 Data and code availability

Example tomograms of yeast and *Anabaena* lamellae milled in a fully automated manner and the final septal junction subtomogram average determined in this study were deposited to the Electron Microscopy Data Bank (accession number EMDB xxx-yyy for the tomograms and zzz for the subtomogram average).

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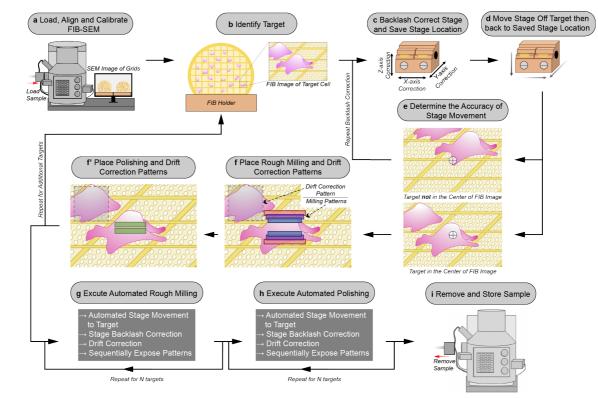
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## 504 Figure 1. Schematic of the automated sequential cryoFIB milling workflow.

a: FIB currents are aligned and calibrated, and the sample is loaded into the FIB-SEMinstrument.

**b**: A target cell is identified on the grid with the FIB.

508 c: To correct for errors in mechanical stage movements, backlash correction of the stage

509 is performed. The resulting stage location is saved in the stage navigator.

**d**: The stage is randomly moved out of position by the user. Using the saved

511 coordinates, the stage is moved back to the target using the saved position in the stage512 navigator.

**e**: The accuracy of this autonomous stage movement is determined by the user. If the

target is not centered in the FIB image, backlash correction is repeated until accurate
targeting is achieved (c-e).

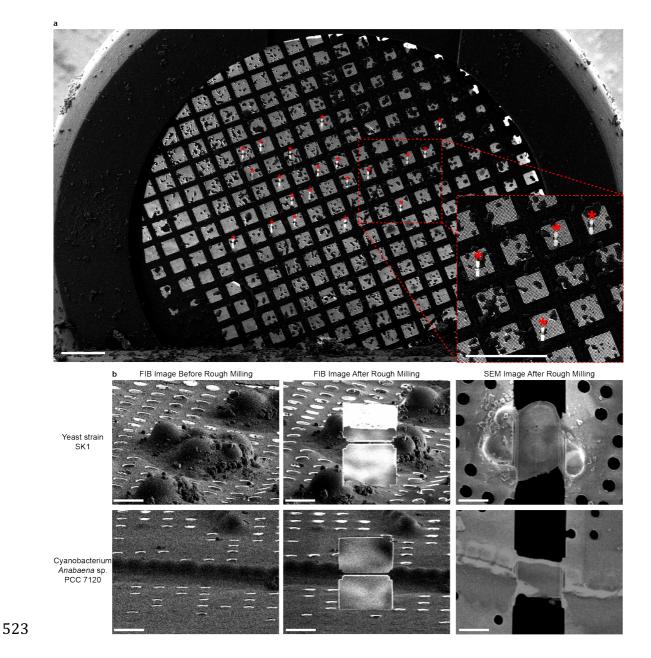
516 **f/f'**: Rough milling, polishing and drift correction patterns are placed onto the image.

517 Rough milling and polishing patterns are saved separately to the queue. The procedure

518 (b-f') is repeated to select additional targets.

- 519 g/h: Rough milling and lamellae polishing are executed automatically.
- 520 i: The grids with milled lamellae are removed and stored.

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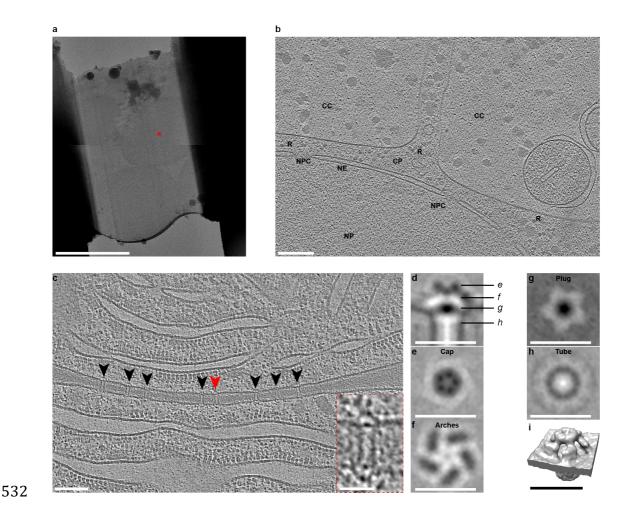


# 524 Figure 2. Representative images of lamellae generated by automated sequential 525 rough milling.

**a:** SEM grid overview image including 20 yeast targets (asterisks) on which rough

527 milling was performed in an automated sequential manner (session C). Bars, 200 μm.

- **b:** Representative SEM and FIB images of yeast and cyanobacterial *Anabaena* cells
- 529 captured before and after fully automated sequential rough milling (session B.1 and
- 530 B.2). Bars, 5 μm.
- 531



# Figure 3. Automated sequential cryoFIB milling results in high-quality lamellae and cryotomograms.

a: CryoTEM overview image of a typical lamella (session C) containing multiple yeast
cells. Red mark indicates the cell imaged in (b). Bar, 5 µm.

**b**: Shown is an 18 nm thick slice through a cryotomogram of a yeast cell (session C)

538 [indicated by red mark in (a)]. The thickness of the lamella was determined to be 225

nm. The tomogram shows a characteristic nucleoplasm (NP), nuclear pore complexes

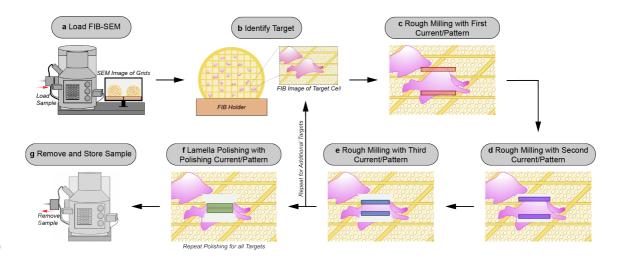
540 (NPC), nuclear envelope (NE), cytoplasm (CP), cytoplasmic ribosomes (R), and other

- 541 cellular compartments (CC). Bar, 200 nm.
- **c**: Shown is a 14 nm thick slice through a cryotomogram of a septum between two
- 543 Anabaena sp. PCC 7120 cyanobacteria cells (session F). The thickness of the lamella
- 544 was determined to be 208 nm. Arrowheads indicate septal junctions. The inset shows a
- 545 magnified view of the septal junction indicated by a red arrowhead. Other cellular
- 546 features are cytoplasmic membranes (CM), phycobilisomes (PB), thylakoid membranes

- 547 (TM) and septal peptidoglycan (PG). Bars, 100 nm and 25 nm (inset).
- 548 d-i: A subtomogram average was generated by 5-fold symmetrizing 343 septal junctions
- that were extracted from nine tomograms. Shown are longitudinal (d) and perpendicular
- 550 (e-h) slices (thickness 0.68 nm) and a surface rendering (i) of the symmetrized average.
- 551 The observed characteristic structural modules were similar to a recent study that
- applied manual cryoFIB milling (Weiss et al., 2019) (also see Supplementary Fig. 3).
- 553 Bars, 25 nm.

# **Table 1. Overview and success rates of milling sessions.**

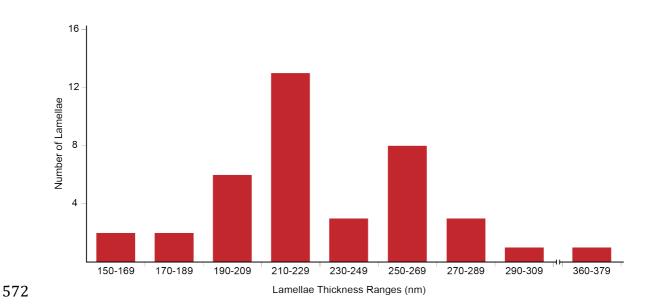
Session	Sample Type	Rough Milling	Rough Milling Success	Polishing	Polishing Success	Comments
А	Cyanobacterium <i>Anabaena</i> sp. PCC 7120	Automated	10/10	Manual	10/10	
B.1	Yeast strain SK1	Automated	5/5	Manual	5/5	Rough milling of both samples
B.2	Cyanobacterium <i>Anabaena</i> sp. PCC 7120	Automated	5/5	Automated	5/5	performed in the same session.
С	Yeast strain SK1	Automated	20/20	Automated	11/20	Lamella were left in instrument for 10h before polishing, leading to lamellae bending and a lower success rate.
D	Cyanobacterium <i>Anabaena</i> sp. PCC 7120	Automated	7/7	Automated	7/7	
E	Cyanobacterium <i>Anabaena</i> sp. PCC 7120	Automated	7/7	Automated	7/7	
F	Cyanobacterium <i>Anabaena</i> sp. PCC 7120	Automated	18/19	Automated	16/18	User selected one target two times for rough milling, leading to failure in rough milling.
		Total Automated	72/73 (99%)	Total Automated	46/57 (81%)	





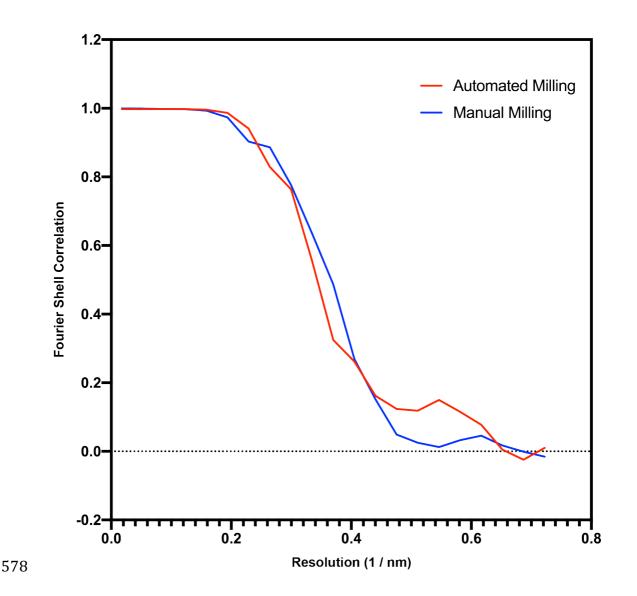
# 557 Supplementary Figure 1. Schematic of the manual cryoFIB milling workflow.

- **a:** The sample is loaded into the FIB-SEM instrument.
- **b:** A target is centered in the FIB image.
- **c-e:** The first pair of rough milling patterns is placed on the target and milling is
- 561 executed (c). Lamellae milling is observed via a live FIB view to determine when a
- 562 milling step is completed. The same procedure is repeated for the second (d) and third
- 563 (e) rough milling patterns. After rough milling of the target is completed, additional
- targets can be milled by repeating steps b-e.
- f: Rough-milled lamellae are polished with a fourth set of milling patterns. Polishing isrepeated for all rough-milled lamellae.
- 567 g: The grids with milled lamellae are removed and stored.
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# 573 Supplementary Figure 2. Distribution of lamellae thickness.

- 574 The plot shows the distribution of the thickness values of fully automated sequential
- 575 FIB-milled lamellae, as determined by cryoET imaging. The final polishing milling
- 576 patterns were spaced 300 nm apart.



579 Supplementary Figure 3. Comparison of data quality between manual and580 automated milling.

581 Shown is a Fourier Shell Correlation (FSC) curve (blue) for the septal junction

subtomogram average shown in Figure 3i (resulting from automated milling). The

second curve (red) results from a dataset published previously (Weiss et al., 2019)

584 (resulting from manual milling) and was calculated with the same number of randomly

585 selected subvolumes after 5-fold symmetrization (n=1715). Both approaches result in a

586 comparable resolution estimate.

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588

# 590 Supplementary Table 1. Dimensions and currents used for each milling pattern

# 591 during automated sequential lamellae preparation.

Milling Patterns 1 and 2 (Rough Milling 1)	30 kV 700 pA 9 x 5 µm rectange Patterns spaced 2 µm apart
Milling Patterns 3 and 4 (Rough Milling 2)	30 kV 300 pA 8 x 2 µm rectange Patterns spaced 1 µm apart
Milling Patterns 5 and 6 (Rough Milling 3)	30 kV 100 pA 7.5 x 1 μm rectange Patterns spaced 500 nm apart
Milling Patterns 7 and 8 (Lamella Polishing)	30 kV 50 pA 7 x 0.5 μm rectange Patterns spaced 300 nm apart
Drift Correction Pattern (Rough Milling and Polishing)	3 x 3 μm rectangle

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